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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **SUNOHARA, Masahiro, et al.**

Group Art Unit: 2826

Serial No.: **10/720,514**

Examiner: **Alexander O. William**

Filed: **November 25, 2003**

P.T.O. Confirmation No.: **5140**

FOR: **ELECTRONIC PARTS PACKAGING STRUCTURE HAVING MUTUALLY CONNECTED ELECTRONIC PARTS THAT ARE BURIED IN AN INSULATING FILM (as amended)**

**AMENDMENT UNDER 37 CFR §1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

October 15, 2004

Sir:

In response to the Office Action dated **August 2, 2004**, please amend the above-identified application as follows:

**Amendments to the Title** are shown on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 9 of this paper.

U.S. Patent Application Serial No. 10/720,514  
Amendment filed October 15, 2004  
Reply to OA dated August 2, 2004

**AMENDMENTS TO THE TITLE:**

Amend the title to read as follows:

ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF  
~~MANUFACTURING THE SAME~~ HAVING MUTUALLY CONNECTED ELECTRONIC  
PARTS THAT ARE BURIED IN AN INSULATING FILM